



July 13, 2017

NEWS RELEASE

Boosting Production Capacity for Electro-deposited Copper Foil for Flexible Printed Circuits

—Aiming for 20% increase in production capacity of Malaysia Plant—

Mitsui Mining & Smelting Co., Ltd. (President: Keiji Nishida; “Mitsui Kinzoku,” hereafter) is pleased to announce that it has decided to increase production capacity of electro-deposited copper foil for flexible printed circuits (FPC, hereafter)*¹ by 20% on a year-on-year basis.

Mitsui Kinzoku’s electro-deposited copper foil for FPC features “Super HTE™”, which has high elongation characteristics and high bending one. The product has earned high marks with customers, and has gained the No. 1 global market share on the strength of its high quality and stable supply.

Recent smartphone market growth and expanded smartphone functionality have led to a significant increase of “Super HTE™” sales volume. To meet this demand Mitsui Kinzoku will revamp two idle surface treatment production lines at the Malaysian plant (Mitsui Copper Foil (Malaysia) SDN.BHD.), to commence operation sequentially from August 2017, thereby boosting production capacity by 20% on a year-on-year basis. This will enable the company to respond to the robust demand for electro-deposited copper foil for FPC.

Under the slogan “Material Intelligence,” Mitsui Kinzoku will maintain stable quality and ensure adequate supply to its customers.

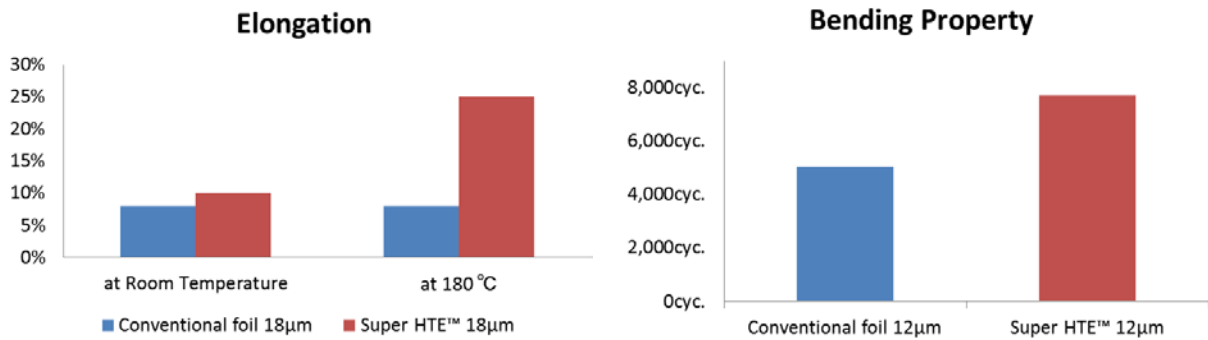
[Inquiries]

Investor Relations and Corporate Communications Department,

Corporate Planning & Control Sector

Mitsui Mining & Smelting Co., Ltd.

Email: PR@mitsui-kinzoku.co.jp



Elongation at room temperature and at 180°C

Results of IPC Flexural Endurance tests

Typical Characteristics of Super HTE™ Electro-deposited Copper Foil for Flexible Printed Circuits

(Addition)

*¹ Flexible Printed Circuits

Flexible circuit boards which has a pattern of conductive traces formed by metals such as copper bonded on a highly flexible thin insulant such as polyimide

(Reference)

Mitsui Copper Foil (Malaysia) SDN. BHD.

- (1) Name Mitsui Copper Foil (Malaysia) SDN. BHD.
- (2) Location Selangor, Malaysia
- (3) President Yuji Tejima
- (4) Established April 1989
- (5) Capital 330,000,000 Malaysian Ringgit
- (6) Investment Mitsui Kinzoku (100%)
- (7) Business Activities Manufacturing of copper foil for printed circuit boards